

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Joseph M. Milewski and : Art Unit:
 Charles G. Woychik : Examiner:
 Serial No.: To Be Assigned :
 Filed: Herewith :
 For: LOW TEMPERATURE SOLDER :
 CHIP ATTACH STRUCTURE :

DIVISIONAL APPLICATION OF:

Applicants: Joseph Milewski and : Art Unit: 1725
 Charles G. Woychik : Examiner: K. Stoner
 Serial No.: 08/815,656 :
 Filed: March 13, 1997 :
 For: PROCESS TO PRODUCE A :
 HIGH TEMPERATURE :
 INTERCONNECTION :

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
 Washington, D.C. 20231

S I R :

Before examining the application first identified above, please
 amend that application as follows.

IN THE TITLE:

Please delete the title in its entirety and substitute therefor:

LOW TEMPERATURE SOLDER CHIP ATTACH STRUCTURE.

1000443-110004
 "FEE" FOOT

IN THE SPECIFICATION:

On page 1, before "FIELD OF THE INVENTION," Insert the following paragraph:

This application is a divisional of U.S. Patent Application Serial Number 08/815,656, filed on March 13, 1997, which has been allowed.

IN THE CLAIMS:

Please cancel claims 1-10.

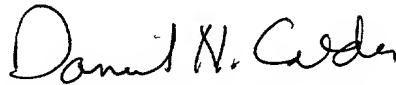
1000442-10004

REMARKS

This is a divisional application of patent application Serial Number 08/815,656. The title and the specification have been amended. Claims 1-10 have been cancelled. Claims 11-19 remain and these claims are presented for examination.

Respectfully submitted,

RATNER & PRESTIA



Daniel N. Calder, Reg. No. 27,424
Attorney for Applicants

DNC/pb

Attachment: Version with Markings to Show Changes Made

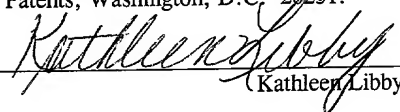
Dated: November 2, 2001

Suite 301
One Westlakes, Berwyn
P.O. Box 980
Valley Forge, PA 19482-0980
(610) 407-0700

The Assistant Commissioner for Patents is hereby authorized to charge payment to Deposit Account No. **09-0457 (IBM Corporation)** of any fees associated with this communication.

EXPRESS MAIL Mailing Label Number: EL 910363993 US
Date of Deposit: November 2, 2001

I hereby certify that this paper and fee is being deposited, under 37 C.F.R. § 1.10 and with sufficient postage, using the "Express Mail Post Office to Addressee" service of the United States Postal Service on the date indicated above and that the deposit is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.


(Kathleen Libby)

VERSION WITH MARKINGS TO SHOW CHANGES MADEIN THE TITLE:

[PROCESS TO PRODUCE A HIGH TEMPERATURE
INTERCONNECTION] LOW TEMPERATURE SOLDER CHIP ATTACH
STRUCTURE.

IN THE SPECIFICATION:

Insert before the first line of the specification --This application
is a divisional of U.S. Patent Application Serial Number 08/815,656, filed on
March 13, 1997, which has been allowed.--

IN THE CLAIMS:

Claims 1-10 have been cancelled.

FOOTNOTES